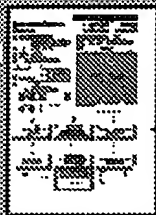


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Inventor(s):

**YASUDA MASAYUKI**

Applicant(s):

**SONY CORP**

Issued/Filed Dates:

**Oct. 9, 1998 / March 21, 1997**

Application Number:

**JP1997000068383**

IPC Class:

**H05K 003/06; H05K 001/09;**

Abstract:

**Problem to be solved:** To form a thin wiring in a simple environment by removing a prescribed part of a resist film by laser abrasion after the resist film showing a resistance to etching is formed on metal foil to serve as conductors and successively resolving the resist and wet-etching the metal foil.

**Solution:** After an etching resist 3 is formed on metal foil, the etching resist is removed by projecting a laser beam 4 upon the conductor removing part of the laminated body from the resist 3 side. Then a desired wiring board is obtained by performing etching on the substrate with resolved resist thus obtained. The resolved resist is stripped off by using a stripping-off solution. Therefore, a printed wiring board can be manufactured in a simple environment without paying attention to the influence of dust, etc.

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Foreign References:

**none**

(No patents reference this one)

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(11) Publication number: **10**

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## PATENT ABSTRACTS OF JAPAN

(21) Application number: **09068383**(51) Intl. Cl.: **H05K 3/06 H05K 1/09**(22) Application date: **21.03.97**

(30) Priority:

(43) Date of application  
publication: **09.10.98**(84) Designated contracting  
states:(71) Applicant: **SONY CORP**(72) Inventor: **YASUDA MASAYUKI**

(74) Representative:

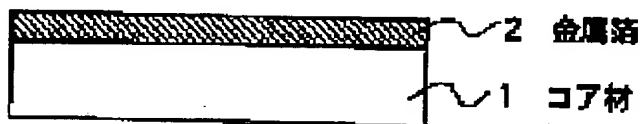
**(54) MANUFACTURE OF  
PRINTED WIRING BOARD**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To form a thin wiring in a simple environment by removing a prescribed part of a resist film by laser abrasion after the resist film showing a resistance to etching is formed on metal foil to serve as conductors and successively resolving the resist and wet-etching the metal foil.

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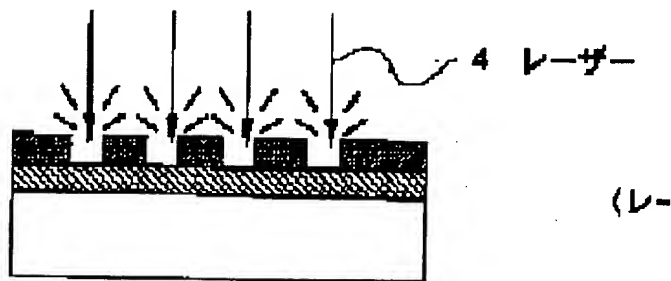
(a)



(b)



(c)



(d)



environment without paying  
attention to the influence of dust, etc.

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